

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUC100N08S5N043	**Issued**	22. April 2022
MA#	MA005705599		
Package	PG-TDSON-8-34	**Weight***	113.06 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.600	1.42	1.42	14150	14150
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		140	
	non noble metal	iron	7439-89-6	0.053	0.05		468	
	non noble metal	copper	7440-50-8	52.842	46.75	46.81	467363	467971
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	391	391
encapsulation	organic material	carbon black	1333-86-4	0.074	0.07		657	
	plastics	epoxy resin	-	5.869	5.19		51912	
	inorganic material	silicondioxide	60676-86-0	31.204	27.60	32.86	275986	328555
leadfinish	non noble metal	tin	7440-31-5	1.574	1.39	1.39	13919	13919
plating	noble metal	silver	7440-22-4	0.209	0.18	0.18	1850	1850
solder	non noble metal	tin	7440-31-5	0.036	0.03		315	
	noble metal	silver	7440-22-4	0.045	0.04		394	
	non noble metal	lead	7439-92-1	1.700	1.50	1.57	15036	15745
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	16.828	14.88	14.89	148832	149026
clip plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5651	5651
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2738	2742
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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